



Intel[®] Server Board SE7501CW2 Memory List Test Report Summary

Revision History		
Date	Rev	Modifications
April/03	0.5	Preliminary release
April/03	1.0	Production Release
May/03	2.0	Added Buffalo and Dataram 256MB parts. Added Dataram, ATP, Smart and Buffalo 512MB parts. (In shaded area)
June/03	3.0	Added ATP, Viking and Centon 256MB parts. Added Dataram, Viking and Buffalo 512MB parts. Added ATP, Viking, Dataram, and Smart 1GB parts. Added Samsung 128MB, 256MB and 1GB parts. Added Infineon 1GB and 2GB parts. (In shaded area)
June/03	4.0	Added Viking 256MB parts. Added Viking and Legend 512MB parts. Added Viking, Avant and Centon 1GB parts. Added Smart 2GB parts. Added Samsung 256MB & 1GB parts. (In shaded area)
July/03	5.0	Added TRS 256MB parts. Added TRS and Legend 512MB parts. Added Buffalo and Legend 1GB parts. Added Micron 256MB part. Added Infineon 256MB, 512MB and 1GB parts. (In shaded area)
July/03	6.0	Added Avant and TRS 512MB parts. Added Infineon 512MB and 1GB parts. Added Micron 512MB part. Added Samsung 1GB parts. (In shaded area)
Aug/03	7.0	Added Ventura & Kingston 512MB parts. Added Viking, Samsung and TRS 1GB parts. (In shaded area) Updated EOL Status.
Sept/03	8.0	Added Kingston 128MB part. (In shaded area)
Sept/03	9.0	Added TRS 2GB parts. (In shaded area)
Oct/03	10.0	Added Avant, ATP and Ventura 512MB parts. Added Ventura 1GB parts. (In shaded area). Also updated EOL status.
Nov/03	11.0	Added Legend 512MB and 1GB parts. Added Avant and Wintec 1GB parts. Added Samsung 512MB part. Correction made to Infineon 512MB and 1GB parts. Correction made to Samsung 1GB part. (In shaded area)
Nov/03	12.0	Added Legend 256MB and 512MB parts. Added ATP and Avant 1GB parts. Added Dataram 2GB parts. (In shaded area)
Nov/03	13.0	Added ATP 1GB parts. Added Legacy 512MB, 1GB and 2GB parts. (In shaded area)
Dec/03	14.0	Added Smart and Legend 1GB parts. Added Kingston 256MB part. (In shaded area)
Jan/04	15.0	Added Kingston and Smart 1GB parts. (In shaded area)
Feb/04	16.0	Added Smart 256MB and 512MB parts. Added Avant and legacy 1GB parts. (In shaded area). Also Updated EOL status.
Feb/04	17.0	Added Dane-Elec 256MB parts. Added Swissbit and Avant 512MB parts. Added Smart, Swissbit, and TRS 1GB parts. New CMTL address. (In shaded area)
Mar/04	18.0	Added ATP 2GB parts. (In shaded area)
Mar/04	19.0	Added Netlist 512MB parts. Added Legacy 1GB and 2GB parts. Added Smart 2GB parts. (In shaded area). Also Updated EOL Status
Apr/04	20.0	Added Ventura 1GB and 512MB parts. Added Legacy 512MB parts. Added Kingston 1GB parts. (In shaded area)
May/04	21.0	Added Ventura 1GB and 2GB parts. Added Legacy, Smart, Avant, ATP and Dataram 1GB parts. (In shaded area)
Jun/04	22.0	Added Centon 512MB parts. (In shaded area)
Jun/04	23.0	Added Viking 512MB, 1GB and 2GB parts. (In shaded area)
July/04	24.0	Added Viking 256MB parts. Added Kingston 2GB parts. (In shaded area)
Aug/04	25.0	Added Dane-Elec and Centon 512MB parts. Added Dataram 1GB parts. (In shaded area)
Sept/04	26.0	Added support for DDR333 modules. Added Legend, TRS, Centon and Buffalo 512MB parts. Added Smart and Wintec 1GB parts. (In shaded area)
Sep/04	27.0	Added Buffalo 512MB and 1GB parts. (In shaded area)
Oct/04	28.0	Added Viking 1GB parts. (In shaded area)
Oct/04	29.0	Added Legend 512MB and 2GB parts. (In shaded area)
Oct/04	30.0	Added Avant 1GB Parts. (In shaded area)
Nov/04	31.0	Added Dane and Buffalo 512MB parts. Added Dane, TRS, and Centon 1GB parts. (In shaded area)
Dec/04	32.0	Added Swissbit and Kingston 1GB parts. (In shaded area)
Dec/04	33.0	Added Smart and Buffalo 1GB parts. (In shaded area)
Feb/05	34.0	Added Apacer 1GB parts and Dataram 2GB parts. (In shaded area)
Mar/05	35.0	Added note on Lead free modules (these modules are now in bold text). Added Apacer 512MB parts. Added Kingston 1GB parts. (In shaded area)

Revision History		
Date	Rev	Modifications
Apr/05	36.0	Added Legend 256MB parts. (In shaded area)
Apr/05	37.0	Added Kingston 2GB parts. (In shaded area)
May/05	38.0	Updated Contact information. Updated Kingston part number from KVR266X72RC25/512 to KVR266S4R25/512i per vendor's request. (In shaded area)
Aug/05	39.0	Added Dataram 1GB parts. (In shaded area)
Aug/05	40.0	Added Kingston 512MB and 1GB parts. (In shaded area)
Oct/05	41.0	Added TRS 2GB part. (In shaded area)
Jan/06	42.0	Added Legend 512MB part. (In shaded area)
Mar/06	43.0	Added Legend 1GB & 2GB parts. (In shaded area)
June/06	44.0	Infineon name change to Qimonda effective May 1 st , 2006. Added Dataram 1G part. (In shaded area)
July/06	45.0	Added Dataram 1GB part. (In shaded area)
Aug/06	46.0	Added Dataram 2GB part. (In shaded area)
Aug/06	47.0	Added Kingston 2GB part. (In shaded area)

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The Intel® Server Board SE7501CW2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7501CW2. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL*)¹. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel's Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft* Windows* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

CMTL* is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690
Fax (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
<http://www.cmtlabs.com/>

Qualified Memory for the Intel® Server Board SE7501CW2

The Intel® server board SE7501CW2 has 4 DIMM sockets supporting up to 8 GB of Registered ECC DDR266 or DDR333 memory using four 72-bit DIMM modules. These four DIMM sockets constitute two memory banks; Bank1 with contiguous sockets labeled DIMM1A & DIMM1B, and Bank2 with contiguous sockets labeled DIMM2A & DIMM2B. Memory must be installed in pairs; DIMM Bank1 must be populated before DIMM Bank2. Memory within a DIMM bank must be identical. For customers requiring a lower cost configuration, a single DIMM may be populated in the DIMM1A socket. If this is done, the Intel® x4 Single Device Data Correction (Intel x4 SDDC) technology and memory interleaving will not be enabled. DIMM and memory configurations must adhere to the following:

DIMM and memory configurations must adhere to the following:

- DDR266 and DDR333 registered ECC 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMM organization: x72 ECC
- Pin Count: 184
- Memory capacity: 128MB, 256MB, 512MB, 1GB and 2GB
- Serial PD: JEDEC Rev 2.0
- Interface: SSTL2
- CAS Latency: 2 & 2.5
- Minimum configuration: 256MB using two 128MB DIMMs in Bank1
- One or two memory banks may be populated

Note: Memory qualification is done by testing identical memory modules in all DIMM sockets. Memory qualification does not include testing of mixed DIMM type and/or vendors; mixing of DIMM type and/or vendors is not recommended.

Below is a chart that lists the current supported memory types:

DDR266 Registered SDRAM Module Configurations for Cas Latency 2 & 2.5					
DIMM Capacity	DIMM Organization	DRAM Density	DRAM Organization	# DRAM Devices/rows/Banks	# Address bits rows/Banks/column
128MB	16M x 72	64Mbit	16M x 4	18/1/4	12/2/10
128MB	16M x 72	64Mbit	8M x 8	18/2/4	12/2/9
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	64Mbit	16M x 4	36/2/4	12/2/10
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	128Mbit	32M x 4	36/2/4	12/2/11
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12

DDR333 Registered DRAM Module Configuration Matrix					
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11

The memory controller in the server board SE7501CW2 supports memory scrubbing, single-bit error correction, multiple-bit error detection and the Intel® x4 Single Device Data Correction (SDDC) support with x4 DIMMs only. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs. The Intel® x4 Single Device Data Correction gives the memory sub-system the ability to withstand a multi-bit failure within a DRAM device, including a failure that causes incorrect data on all data bits of the device.

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7501CW2. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

For a full description of the Intel® server board SE7501CW2 memory features refer to the *Intel® Server Board SE7501CW2 Technical Product Specification* available on-line at <http://support.intel.com/support/motherboards/server/SE7501CW2>

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

Note: This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

This list is subject to change without notice.

Server Board SE7501CW2

**Registered, ECC, DDR266 DIMM Modules
128MB Sizes (16Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M383L1713DT-S-CA2	K4H280838D-TCA2	Samsung		3/4/03	2		(16Mx8)*9	
Micron	MT9VDDT1672G-265B2	MT46V16M8-75 B	Micron		3/26/03	2.5	Yes	(16Mx8)*9	
~ Qimonda (Infineon)	HYS72D16000GR-7-A	HYB25D12880OAT-7	~ Qimonda (Infineon)		4/7/03	2		(16Mx8)*9	
Samsung	M383L1713ETS-CB0	K4H280838E-TCB0	Samsung		5/30/03	2.5		(16Mx8)*9	
Kingston	KVR266X72RC25/128	HY5DU28822BT-H	Hynix		8/27/03	2.5	Yes	(16Mx8)*9	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

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**Registered, ECC, DDR266 DIMM Modules
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L3310DT0-CA2	K4H280438D-TCA2	Samsung		3/10/03	2		(32Mx4)*18	
Micron	MT9VDDT3272G-265B2	MT46V32M8-75 B	Micron		3/19/03	2.5		(32Mx8)*9	
~ Qimonda (Infineon)	HYS72D32001GR-7-A	HYB25D12840OAT-7A	~ Qimonda (Infineon)		3/31/03	2		(32Mx4)*18	
+Buffalo	DD266-R256/SD	K4H280838D-TCB0 rev D	Samsung	RCE0501-AB	4/18/03	2.5		(16Mx8)*18	
+Dataram	DTM63640B	MT46V32M4TG-75 rev B	Micron	40581A rev A	4/21/03	2.5	Yes	(32Mx4)*18	
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/24/03	2.5	Yes	(32Mx8)*9	
+Buffalo	DD266-R256/SE	K4H280838E-TCB0 rev E	Samsung	RCE0502-AA	4/24/03	2.5		(16Mx8)*18	
+ATP Electronics	AB32L72Q8SQB0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1	4/30/03	2.5	Yes	(32Mx8)*9	EOL
Samsung	M383L3310ETS-CB0	K4H280438E-TCB0	Samsung		5/9/03	2.5		(16Mx8)*18	
+Viking	VI4CR327228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000905A	5/14/03	2.5	Yes	(32Mx8)*9	EOL
+Viking	VI4CR327224CTHL1	K4H280438D-TCB0 rev D	Samsung	03-0291 Rev A	5/14/03	2.5	Yes	(32Mx4)*18	EOL
+Centon Electronics	TOP02-D004D	MT46V32M4TG-75 rev B	Micron	LE36DDT1844R rev A	5/12/03	2.5	Yes	(32Mx4)*18	EOL
+Centon Electronics	TOP02-D007G	MT46V32M4TG-75 rev B	Micron	LE36DDT1844R rev A	5/21/03	2.5	Yes	(32Mx4)*18	EOL
+Viking	VI4CR327228DTHL2	MT46V32M8TG-75 rev B	Micron	0000905A	5/23/03	2.5	Yes	(32Mx8)*9	EOL

**Registered, ECC, DDR266 DIMM Modules
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Viking	VI4CR327228D THL3	MT46V32M8TG -75 rev C	Micron	0000905A	5/27/03	2.5	Yes	(32Mx8)*9	
Samsung	M383L3310DTS -CA2	K4H280438D- TCA2	Samsung		6/5/03	2		(32Mx4)*18	
+TRS* Tele-Radio- Space GmbH	TRS21150	HYB25D25680 0BT-7 rev B	~ Qimonda (Infineon)	M0529LA1 rev 1	6/16/03	2	Yes	(32Mx8)*9	
Micron	MT9VDDT3272 G-265C3	MT46V32M8-75 C	Micron		7/3/03	2.5	Yes	(32Mx8)*9	
~ Qimonda (Infineon)	HYS72D32501 GR-7-A	HYB25D12840 0AT-7	~ Qimonda (Infineon)		7/7/03	2	Yes	(32Mx4)*18	
+Legend	L3272YC5- RU1HDC5B	HY5DU56822B T-J rev B	Hyundai	DRR1U0818 -A rev 1	10/27/03	2.5	Yes	(32Mx8)*9	
Kingston	KVR266X72RC 25/256		Micron		7/28/03	2.5	Yes	(32Mx8)*9	
+Smart Modular Technologies	SM3272RDDR3 20LP-I	HYB25D25680 0BT-7 rev B	~ Qimonda (Infineon)	184-L13-2	1/15/04	2	Yes	(32Mx8)*9	
+Smart Modular Technologies	SM3272RDDR3 25LP-S	K4H560838E- TCB0 rev E	Samsung	M312L3313 ETS	1/07/04	2.5	Yes	(32Mx8)*9	
+Dane-Elec	ODLD266R0723 25I-1MC	MT46V32M8TG -6T rev C	Micron	DR1G872-A rev A	1/30/04	2.5	Yes	(32Mx8)*9	
+Viking	VI4CR327228D THL4	MT46V32M8TG (P)-6T rev G	Micron	0000985A	7/1/04	2.5	Yes	(32Mx8)*9	

**Registered, ECC, DDR333 DIMM Modules
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L3272YC6- RU1HDC5B	HY5DU56822B T-D43 rev B	Hyundai	DRR1U0818 -A rev 1	3/25/05	2.5	Yes	(32Mx8)*9	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

Server Board SE7501CW2

**Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D6450 0GR-7-B	HYB25D25640 0BT-7	~ Qimonda (Infineon)		3/7/03	2	Yes	(64Mx4)*18	
Samsung	M312L6420D T0-CA2	K4H560438D- TCA2	Samsung		3/21/03	2	Yes	(64Mx4)*18	
Samsung	M383L6420D TS-CA2	K4H560438D- TCA2	Samsung		4/3/03	2		(64Mx4)*18	
Micron	MT18VDDT6 472G-265C3	MT46V64M4- 75 C	Micron		4/14/03	2.5	Yes	(64Mx4)*18	
+Dataram	DTM63641G	MT46V64M4T G-75 rev C	Micron	40581A rev A	4/16/03	2.5	Yes	(64Mx4)*18	
Samsung	M312L6420E TS-CA2	K4H560838E- TCA2	Samsung		4/17/03	2	Yes	(64Mx4)*18	
+Smart Modular Technologies	SM6472RDD R3H1LP-N	NT5DS64M4A T-7K	Nanya	P52G184NES Z6G001 rev A	4/17/03	2.5	Yes	(64Mx4)*18	
+ATP Electronics	AB64L72Q8S 8B0S	K4H560838D- TCB0 rev D	Samsung	SB184Q08L1 rev 1	4/18/03	2.5	Yes	(32Mx8)*18	EOL
+Buffalo	DD266- R512/SD	K4H560838D- TCB0 rev D	Samsung	RCE0501-AB	4/21/03	2.5		(32Mx8)*18	
+Buffalo	DD266- R512/MB	MT46V32M8- 75 rev B	Micron	RCE0501-AB	4/21/03	2.5		(32Mx8)*18	
+Buffalo	DD266L- R512/SD	K4H560838D- TCB0 rev D	Samsung	1D188EF-AA	4/24/03	2.5	Yes	(32Mx8)*18	
+Dataram	DTM63641E	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	40581A rev A	5/14/03	2.5	Yes	(64Mx4)*18	EOL
+Viking	VI4CR64722 4DTHL1	K4H560438D- TCB0 rev D	Samsung	03-0291 rev A	5/2/03	2.5	Yes	(64Mx4)*18	EOL
+Viking	VI4CR64722 8DTHL1	K4H560838D- TCB0 rev D	Samsung	0000905AG	5/7/03	2.5	Yes	(32Mx8)*18	EOL
Samsung	M312L6420 DT0-CAA	K4H560438D- TCAA	Samsung		5/7/03	2	Yes	(64Mx4)*18	
+Viking	VI4CR64722 8DTHL2	K4H560838D- TCB0	Samsung	0000905A	5/19/03	2.5	Yes	(32Mx8)*18	EOL
+Buffalo	DD266- R512/SD	K4H560838D- TCB0 rev D	Samsung	RCE0501-AB	5/19/03	2.5		(32Mx8)*18	
+Viking	VI4CR64722 8DTHL3	MT46V32M8T G-75 rev B	Micron	0000905A	5/12/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CR64722 8DTHL4	MT46V32M8T G-75 rev C	Micron	0000905A rev A	5/12/03	2.5	Yes	(32Mx8)*18	
Samsung	M383L6420E TS-CB0	K4H560438E- TCB0	Samsung		5/27/03	2.5		(64Mx4)*18	
+Viking	VI4CR64722 4DTHL2	MT46V64M4T G-75 rev B	Micron	03-0291 rev A	5/23/03	2.5	Yes	(64Mx4)*18	EOL
+Legend	L6472YC5- PPASDC5D	K4H560438D- TCB0 rev D	Samsung	18-25141A rev A	6/10/03	2.5	Yes	(64Mx4)*18	EOL
+Legend	L6472TC5- RR2HDC5A	HY5DU56822 AT-H rev A	Hyundai	DRR720818A rev 2	6/11/03	2.5		(32Mx8)*18	EOL
+TRS* Tele-Radio-Space GmbH	TRS21151	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	M0530LA1 rev 1	6/16/03	2	Yes	(64Mx4)*18	

**Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+TRS* Tele-Radio-Space GmbH	TRS21152	HYB25D25680 0BT-7 rev B	~ Qimonda (Infineon)	M0529LA1 rev 1	6/26/03	2	Yes	(32Mx8)*18	
~ Qimonda (Infineon)	M383L6420E TS-CB0	HYB25D25640 0BT-7	~ Qimonda (Infineon)		6/28/03	2		(64Mx4)*18	
~ Qimonda (Infineon)	HYS72D6432 0GBR-7-B	HYB25D25680 0BC-7	~ Qimonda (Infineon)		7/10/03	2	Yes	(32Mx8)*18	
Micron	MT18VDDT6 472G-262C3	MT46V64M4- 75E C	Micron		7/11/03	2.5	Yes	(64Mx4)*18	
+Avant Technology	AVM7264R3 8C5266K0-A	MT46V64M4T G-75 C rev C	Micron	50-1415-01-B rev B	7/16/03	2.5	Yes	(64Mx4)*18	EOL
Kingston	KVR266S4R 25/512i	HYB25D25640 0BT-7	~ Qimonda (Infineon)		7/10/03	2.5	Yes	(32Mx8)*18	
+Ventura Technology Group	D52WPK31R V	NT5DS64M4B T-75 rev B	Nanya	V218	7/21/03	2.5	Yes	(64Mx4)*18	
+Avant Technology	AVM7264R3 8C5266K0-A	NT5DS64M4B T-75B rev B	Nanya	50-1415-01-B rev B	9/19/03	2.5	Yes	(64Mx4)*18	
+ATP Electronics	AB64L72Q8S 8B0S	K4H560838E- TCB3 rev E	Samsung	SB184Q08L1	9/26/03	2.5	Yes	(32Mx8)*18	
+Ventura Technology Group	D52WVK25S V	K4H560838E- TCB3 rev E	Samsung	V208	9/18/03	2.5	Yes	(32Mx8)*18	
+Legend	L6472YC5- 182HDD5A	HY5DU56422 AT-K rev A	Hyundai	184RL rev 2	10/2/03	2.5	Yes	(64Mx4)*18	
+Legend	L6472YC5- RU1HDC5B	HY5DU56822 BT-J rev B	Hyundai	DRR1U0818-A rev 1	10/27/03	2.5	Yes	(32Mx8)*18	
+Legacy Electronics Inc.	88L6JDLLR- 1LDG	LED64408TA- 6	Legacy	LE36DDT1844 R rev A	11/20/03	2.5	Yes	(64Mx4)*18	
+Smart Modular Technologies	SM6472RDD R325LP-S	K4H560438E- TCB0 rev E	Samsung	M312L3310ET S	1/15/04	2.5	Yes	(64Mx4)*18	
+Swissbit	SDR06472D1 B22IN-75	HYB25D25680 0BT-6 rev B	~ Qimonda (Infineon)	BRDA80A	2/17/04	2	Yes	(32Mx8)*18	
+Avant Technology	AVM7264R3 9C5266K1-A	MT46V32M8T G-75 rev G	Micron	50-1411-01-A rev A	1/27/04	2.5	Yes	(32Mx8)*18	
Netlist, Incorporated	NL9647RD64 042-D21JPA	V58C2256404 SAT7 rev A	Mosel Vitellic	0197-10 rev A	3/12/04	2.5	Yes	(64Mx4)*18	
+Legacy Electronics Inc.	88S6JDLLR- 1JDG	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	LE36DDT1844 R rev A	3/19/04	2	Yes	(64Mx4)*18	
+Ventura Technology Group	D52WVK25M V3	MT46V32M8T G-6T rev C	Micron	V208	4/9/04	2.5		(32Mx8)*18	
+Centon Electronics	TOP02- E003C	V58C2256804 SAT6 rev A	Mosel Vitellic	DR1G872-A	5/13/04	2.5	Yes	(32Mx8)*18	
+Viking	VI4CR64722 8DTHL5	MT46V32M8T G(P)-6T rev G	Micron	0000985A	6/4/04	2.5	Yes	(32Mx8)*18	
+Dane-Elec	DLD266R072 642H	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	0303	7/19/04	2	Yes	(64Mx4)*18	
+Centon Electronics	TOP02- E008H	MT46V64M8T G(P)-6T rev C	Micron	DR1G872 rev A	7/19/04	2	Yes	(64Mx8)*9	

**Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L6472YC5-PPASDD5D	K4H560438D-TCB3 rev D	Samsung	18-25141A Rev A	8/16/04	2.5	Yes	(64Mx4)*18	
+TRS	TRS21202	HYB25D25640 OCE-7 rev C	~ Qimonda (Infineon)	M0530LA1 rev 1	8/10/04	2	Yes	(64Mx4)*18	
+Centon Electronics	TOP02-E007G	MT46V64M8T G(P)-6T rev C	Micron	DR1G872 rev A	8/12/04	2.5	Yes	(64Mx8)*9	
+Dane-Elec	DLD266R072 642H	MT46V64M4T G(P)-6T rev G	Micron	0303	11/8/04	2	Yes	(64Mx4)*18	
+Apacer	77.10709.332	HYB25D25680 OCE-6 rev C	~ Qimonda (Infineon)	48.18115.012 rev 2	3/4/05	2	Yes	(32Mx8)*18	

**Registered, ECC, DDR333 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333L-R512/MG	MT46V32M8T G(P)-6T rev G	Micron	1D188EF-AA	8/27/04	2.5	Yes	(32Mx8)*18	
+Legend	L6472YC6-RU1HDC5D	HY5DU56822 DT-J rev D	Hyundai	DRR1U0818-A1 rev 1	9/30/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333L-R512/SF	K4H560838F-TCB3 rev F	Samsung	1D188EF-AA	11/4/04	2.5	Yes	(32Mx8)*18	
+Kingston	KVR333S4R 25/512I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na	08/08/05	2.5	Yes	(64Mx4)*18	
+Legend	L6472YC6-RU1HDHSC	HY5DU12822 CTP-J rev C	Hynix	DDR1U0818 rev A	12/15/05	2.5	Yes	(64Mx8)*9	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

Server Board SE7501CW2

**Registered, ECC, DDR266 DIMM Modules
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L2828DT0-CA2	K4H560438D-TCA2	Samsung		3/13/03	2	Yes	(64Mx4)*36	
~ Qimonda (Infineon)	HYS72D128500GR-7-A	HYB25D512400AT-7	~ Qimonda (Infineon)		3/17/03	2	Yes	(128Mx4)*18	
+Dataram	DTM63621F	HYB25D256400BT-7 rev B	~ Qimonda (Infineon)	40556 rev B	4/30/03	2	Yes	(64Mx4)*36	
+ATP Electronics	AB28L72P4SM B0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1	4/30/03	2.5	Yes	(64Mx4)*36	EOL
+Dataram	DTM63653B	HYB25D256400BC-7 rev B	~ Qimonda (Infineon)	40599A rev A	5/2/03	2.5	Yes	(64Mx4)*36	EOL
+ATP Electronics	AB28L72T4SQB 0S	K4H560438D-TCB0 rev D	Samsung	SB184T04L2 rev 2	5/7/03	2.5		(64Mx4)*36	EOL
~ Qimonda (Infineon)	^HYS72D128320GBR-7F-B	HYB25D256400BC-7F	~ Qimonda (Infineon)		5/14/03	2	Yes	(64Mx4)*36	
+Viking	VI4CR287224D YHL1	K4H560438D-TCB0 rev D	Samsung	03-0291 Rev A	5/19/03	2.5	Yes	(64Mx4)*36	EOL
Samsung	M312L2920MT0-CB0	K4H510438M-TCB0	Samsung		5/20/03	2.5	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR 301LP-N	17329-02	Nanya	P51G184NES ZK002 rev A	5/21/03	2	Yes	(64Mx4)*36	
+Centon Electronics	TOP02-D006F	MT46V64M4TG-75C rev C	Micron	LE36DDT1844 R rev A	5/23/03	2.5	Yes	(64Mx4)*36	EOL
+Viking	VI4CR287224D YHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	5/27/03	2.5	Yes	(64Mx4)*36	EOL
+Avant Technology	AVM7228R82C 5266K1-A	MT46V64M4TG-75 rev C	Micron	50-1416-01-A rev A	6/6/03	2.5	Yes	(64Mx4)*36	
+Legend	L1272YC5-PPBSDD5D	K4H560438D-TCB0 rev D	Samsung	18-21040B rev B	6/11/03	2.5	Yes	(64Mx4)*36	EOL
Samsung	M312L2828DT0-CB0	K4H510638D-TCB0	Samsung		6/18/03	2.5	Yes	(64Mx4)*36	
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	6/18/03	2	Yes	(64Mx4)*36	
Samsung	M312L2828ET0-CA2	K4H510638E-TCA2	Samsung		6/24/03	2	Yes	(64Mx4)*36	
~ Qimonda (Infineon)	HYS72D128521GR-7-B	HYB25D256400BT-7	~ Qimonda (Infineon)		7/1/03	2	Yes	(64Mx4)*36	
Samsung	M383L2828ET1-CB0	K4H510638E-TCB0	Samsung		7/8/03			(64Mx4)*36	
+TRS* Tele-Radio-Space GmbH	TRS21153	HYB25D256400BT-7 rev B	~ Qimonda (Infineon)	M0531LA1 rev 1	7/29/03	2	Yes	(64Mx4)*36	
+Viking	VI4CR287224D YHL3	MT46V64M4TG-75 rev C	Micron	03-0291 rev A	7/31/03	2.5	Yes	(64Mx4)*36	
Samsung	◊M312L2828ET0-CAA	K4H510638E-TCAA	Samsung		8/21/03	2	Yes	(64Mx4)*36	
+Ventura Technology Group	D54WPK28SV	K4H560438E-TCB0 rev E	Samsung	V213	9/15/03	2.5		(64Mx4)*36	
+Legend	L1272YC5-183HDD5A	HY5DU56422A S-H rev A	Hyundai	184RL rev 3	10/3/03	2.5	Yes	(64Mx4)*36	

**Registered, ECC, DDR266 DIMM Modules
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Wintec Industries	35952756L	HYB25D25640 0AT-7 rev A	~ Qimonda (Infineon)	ZK2048M84R BYJ	9/30/03	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R82C 5266K1-A	NT5DS64M4BT -75B rev B	Nanya	50-1416-01-A rev A	10/8/03	2.5	Yes	(64Mx4)*36	
+ATP Electronics	AB28L72P4SM B0S	K4H560438E- TCB0 rev E	Samsung	SB184P04L1	11/5/03	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R38C 5266K3-A	NT5DS64M4BT -75B rev B	Nanya	BRDB45A rev A	10/10/03	2.5		(64Mx4)*36	
+Legacy Electronics Inc.	89L6MDLR- 1LDG	LED128408TA- 6	Legacy	LE36DDT1844 R rev A	11/17/03	2.5	Yes	(128Mx4)*18	
+ATP Electronics	AB28L72U4SQ B0S	K4H560438E- TCB0 rev E	Samsung	SB184U04L1	11/12/03	2.5		(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR 301LP-I	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	P54G184NES ZKRCN rev A	12/10/03	2	Yes	(64Mx4)*36	
+Legend	L1272YC5- RU1HDH5A	HY5DU12822A T-H rev A	Hyundai	DRR1U0818-A rev 1	12/10/03	2.5	Yes	(64Mx8)*18	
Kingston	KVR266X72RC 25/1024	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	2025148- 001.A00	12/22/03	2.5	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR 301BG-I	HYB25D25640 0BC-6 rev B	~ Qimonda (Infineon)	P54G184NES ZBRCD rev A	12/15/03	2	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R53C 5266K0-A	MT46V128M4T G-6T rev C	Micron	50-1415-01-B rev B	1/22/04	2.5	Yes	(128Mx4)*18	
+Legacy Electronics Inc.	89L6MDAR- 1G00	LED128408TA- 6	Legacy	LE512R72DD R rev A	1/22/04	2.5		(128Mx4)*18	
+Swissbit	SDR12872C1A2 2IN-70	HYB25D25640 0BC-7 rev B	~ Qimonda (Infineon)	B6R400	2/2/04	2	Yes	(64Mx4)*36	
+TRS	TRS21174	HYB25D51280 0AT-7 rev A	~ Qimonda (Infineon)	M0529LA1 rev 1	2/5/04	2	Yes	(64Mx8)*18	
+TRS	TRS21171	HYB25D25640 0BC-7 rev B	~ Qimonda (Infineon)	M0533LA1 rev 1	2/13/04	2	Yes	(64Mx4)*36	
+Smart Modular Technologies	SM12872RDDR 301HP-I	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	P58G184NES ZKGA1	2/11/04	2		(64Mx4)*36	
+Legacy Electronics Inc.	89L6JDGR- 1LDG	LED64408TA-6 rev B	Legacy	LE36DDF1844 RLP rev A	3/8/04	2.5	Yes	(64Mx4)*36	
Kingston	KVR266X72RC 25/1024	K4H510438B- TCB0 rev B	Samsung	2025127- 001.A00	4/12/04	2.5	Yes	(128Mx4)*18	
+Ventura Technology Group	D54WCK34SV	K4H560438E- GCB3 rev E	Samsung	V223	3/17/04	2.5	Yes	(64Mx4)*36	
+Legacy Electronics Inc.	89S6JDLC- 1JDG	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	LE36DDT1844 R rev A	4/23/04	2	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R52C 5266K1-A	MT46V64M8TG (P)-75 rev C	Micron	50-1411-01-A rev A	4/23/04	2.5	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872RDDR 301BGAS	K4H560438E- GCB3 rev E	Samsung	P54G184NES ZBRCD	4/19/04	2	Yes	(64Mx4)*36	
+Dataram	DTM63653H	HYB25D25640 0BC-6 rev B	~ Qimonda (Infineon)	40599A rev A	4/16/04	2	Yes	(64Mx4)*36	

**Registered, ECC, DDR266 DIMM Modules
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Ventura Technology Group	D54WYK25SV	K4H510838B-TCB3 rev B	Samsung	V208	4/14/04	2.5		(64Mx8)*18	
+ATP Electronics	AB28L72Q8SH B0S	K4H510838B-TCB3 rev B	Samsung	SB184Q08L1 rev 1	5/6/04	2.5	Yes	(64Mx8)*18	
+Viking	VI4CR287228E THL1	MT46V64M8TG (P)-75 rev D	Micron	0000985A	6/3/04	2.5	Yes	(64Mx8)*18	
+Dataram	DTM63698B	HYB25D51240 0BE-7 rev B	~ Qimonda (Infineon)	40581A rev A	7/13/04	2	Yes	(128Mx4)*18	
+Smart Modular Technologies	SX12872RDDR 308BTIB	HYB25D51280 0BE-6 rev B	~ Qimonda (Infineon)	P52G184NEB Z6RCL rev B	8/27/04	2	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872RDDR 301BGIC	HYB25D25640 0CC-6 rev C	~ Qimonda (Infineon)	P54G184NES ZBRCD	7/29/04	2	Yes	(128Mx4)*18	
+Wintec Industries	3C953641-L	HYB25D25640 0BC-6 rev B	~ Qimonda (Infineon)	ZK4096M84R CJB	8/10/04	2.5	Yes	(128Mx4)*18	
+Dane-Elec	DLD266R07228 5M	MT46V128M4T G(P)-75 rev D	Micron	0303	11/10/04	2.5	Yes	(128Mx4)*18	
+TRS	TRS21203	HYB25D51240 0BE-7 rev B	~ Qimonda (Infineon)	M0530LA1 rev 1	11/5/04	2	Yes	(128Mx4)*18	
+Smart Modular Technologies	SX12872RDDR 302LPIB	HYB25D51240 0BE-7 rev B	~ Qimonda (Infineon)	P52G184NES Z6G001 rev A	11/29/04	2	Yes	(128Mx4)*18	
+Apacer	76.02220.013	HYB25D51280 0BE-6 rev B	~ Qimonda (Infineon)	48.18115.012 rev 2	1/28/05	2	Yes	(64Mx8)*18	
Kingston	KVR266D4R25/ 1GI	HYB25D25640 0BT-7 rev B	~ Qimonda (Infineon)	2025148-001.A00	3/8/05	2.5	Yes	(64Mx4)*36	
+Dataram	DTM63698C	HYB25D51240 0BT(BE)-6 rev B	~ Qimonda (Infineon)	40581A rev A	7/5/05	2	Yes	(128Mx4)*18	
Dataram	DTM63653R	HYB25D25640 0CF-6 rev C	Qimonda (Infineon)	40599A rev A	04/28/06	2	Yes	(64Mx4)*36	
Dataram	DTM63698D	HYB25D51240 0CE-6 rev C	Qimonda (Infineon)	40581A rev A	5/5/06	2	Yes	(128Mx4)*18	

**Registered, ECC, DDR333 DIMM Modules
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333L-R1G/SB	K4H510838B-TCB3 rev B	Samsung	1D188EF-AA	9/1/04	2.5	Yes	(64Mx8)*18	
+Viking	VI4CR287224D BKL2	K4H560438E-GCB3 rev E	Samsung	0000972B	9/17/04	2.5	Yes	(64Mx4)*36	
+Avant Technology	AVM7228R38C 5333K3-A	MT46V64M4TG (P)-6T rev C	Micron	BRDB45A rev A	10/20/04	2.5		(64Mx4)*36	
+TRS	TRS21197	HYB25D25640 0CC-6 rev C	~ Qimonda (Infineon)	M0533LA1 rev 1	11/12/04	2.5	Yes	(64Mx4)*36	
+Centon Electronics	TOP02-E150	K4H560438E-GCB3 rev E	Samsung	CPCB/00571 rev G	11/11/04	2.5	Yes	(64Mx4)*36	
+Swissbit	SDR12872C1A2 2IN-60	HYB25D25640 0BC-6 rev B	~ Qimonda	B6R400 rev A	11/17/04	2.5	Yes	(64Mx4)*36	

Registered, ECC, DDR333 DIMM Modules 1GB Sizes (128Mx72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Kingston	KVR333X72RC 25/1GD	HYB25D51280 0BE-6 rev B	~ Qimonda (Infineon)	205128-001.A00	11/19/04	2.5	Yes	(64Mx8)*18	
+Buffalo	DD333L-R1G/MD	MT46V64M8TG (P)-6T rev D	Micron	1D188EF-AA	12/3/04	2.5	Yes	(64Mx8)*18	
+Kingston	KVR333D4R25/1GI	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na	08/02/05	2.5	Yes	(64Mx4)*36	
+Legend	L1272YC6-PPXSMD1B	K4H510438B-GCB3 rev B	Samsung	M312L6420G0 na	2/14/06	2.5	Yes	(128Mx4)*18	
+Legend	L1272YC6-PPXSDD2E	K4H560438E-GCB3 rev E	Samsung	DR2G472B na	2/23/06	2.5	Yes	(64Mx4)*36	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

Server Board SE7501CW2

**Registered, ECC, DDR266 DIMM Modules
2GB Sizes (256Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D256520GR-7-A	HYB25D512400AT-7	~ Qimonda (Infineon)		3/19/03	2	Yes	(128Mx4)*36	
Samsung	M312L5628MT0-CB0	K4H1G0638M-TCB0	Samsung		4/29/03	2.5	Yes	(128Mx4)*36	
~ Qimonda (Infineon)	^HYS72D256520GR-7F-A	HYB25D512400AT-7F	~ Qimonda (Infineon)		5/14/03	2	Yes	(128Mx4)*36	
+Smart Modular Technologies	SM25672RDDR301LP-I	HYB25D512400AT-7 rev A	~ Qimonda (Infineon)	P54G184NESZKRCN rev A	5/30/03	2	Yes	(128Mx4)*36	
+TRS* Tele-Radio-Space GmbH	TRS21155	HYB25D512400AT-7 rev A	~ Qimonda (Infineon)	M0531LA1 rev 1	9/2/03	2	Yes	(128Mx4)*36	
+Dataram	DTM63663B	HYB25D512400AT-7 rev A	~ Qimonda (Infineon)	40556 rev B	10/15/03	2	Yes	(128Mx4)*36	
+Legacy Electronics Inc.	8AL6MDLC-1LDG	LED128408TA-6	Legacy	LE36DDT1844R rev A	11/24/03	2.5	Yes	(128Mx4)*36	
+ATP Electronics	AB56L72P4SM B0M	MT46V128M4T G-75 rev C	Micron	SB184P04L1	2/20/04	2.5	Yes	(128Mx4)*36	
+Legacy Electronics Inc.	8AS6MDLC-1JDG	HYB25D512400AT-7 rev A	~ Qimonda (Infineon)	LE36DDT1844R	3/10/04	2	Yes	(128Mx4)*36	
+Smart Modular Technologies	SM25672RDDR301HP-I	HYB25D512400AT-7 rev A	~ Qimonda (Infineon)	P52G184NESZKGA1	3/3/04	2		(128Mx4)*36	
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213	4/20/04	2.5		(128Mx4)*36	
+Viking	VI4CR567224EYHL3	K4H510438B-TCB3 rev B	Samsung	03-0307 rev B	6/10/04	2.5	Yes	(128Mx4)*36	
Kingston	KVR266X72RC25/2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00	6/21/04	2.5	Yes	(128Mx4)*36	
+Dataram	DTM63663D	DD5104ADTA-7A rev D	Elpida	40556 rev B	1/20/05	2	Yes	(128Mx4)*36	
+TRS	TRS21218	HYB25D512400BE-7 rev B	~ Qimonda (Infineon)	M0531LA1 rev 1	9/21/05	2	Yes	(128Mx4)*36	
Dataram	DTM63689J	HYB25D512400CF-6 rev C	Qimonda (Infineon)	40020A rev A	7/26/06	2	Yes	(128Mx4)*36	

**Registered, ECC, DDR333 DIMM Modules
2GB Sizes (256Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L2572YC6-PPXSMD5B	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B	10/5/04	2.5	Yes	(128Mx4)*36	
+Kingston	KVR333D4R25/2GI	HYB25D512400BC-6 rev B	~ Qimonda (Infineon)	2025294-001.A00	4/12/05	2.5	Yes	(128Mx4)*36	
+Kingston	KVR333D4R25/2GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na	10/19/05	2.5	Yes	(128Mx4)*36	
+Legend	L2572YC6-PPXSMDMB	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B (0403)	2/7/06	2.5	Yes	(128Mx4)*36	
Kingston	KVR333D4R25/2GI	K4H510438C-ZCB3 rev C	Samsung	2025294-001.A00 na	7/28/06	2.5	Yes	(128Mx4)*36	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpinc.com/	Albert Chung Tel: (1) 408-732-5831, Ext 5858 Fax: (1) 408-732-5055 sales@atpinc.com
ATP Electronics -- Taiwan Inc.	http://www.atpinc.com/	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 phenke@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.heacom/	
Infineon	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itaucocom.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/ http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com

Vendor Name	Web URL	Vendor Direct Sales Info
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements	http://www.peripheral.com/	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	http://www.smartm.com/channel	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vender Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 Andreas.gruendl@trs-eu.com
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 599-0080 ext. 1
Viking InterWorks	http://www.vikinginterworks.com	
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Legend	http://www.legend.com.au	Tel: 800-338-2361 Fax: 949-459-8577 orderdesk@vikingcomponents.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar device type or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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